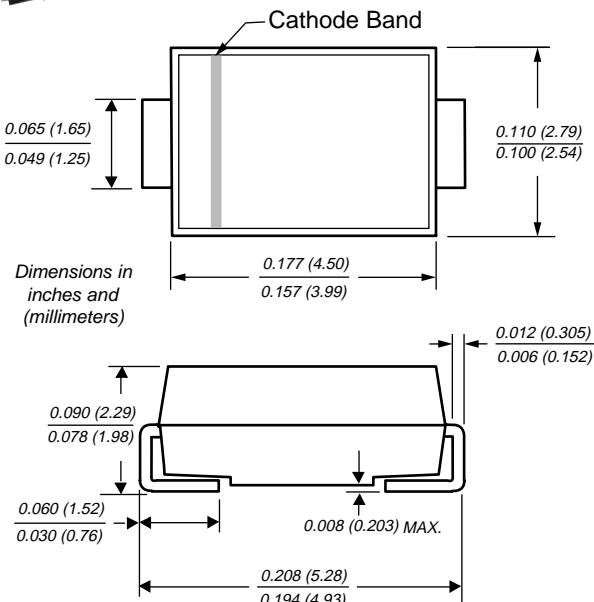



DO-214AC (SMA)


Mechanical Data

Case: JEDEC DO-214AC molded plastic body over passivated chip

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

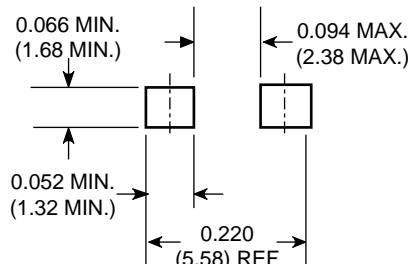
Weight: 0.002oz., 0.064g

Reverse Voltage 200 to 600V
Forward Current 1.6A

Surface Mount Ultrafast Rectifiers

New Product

Mounting Pad Layout



Features

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- For surface mount applications
- Glass passivated chip junctions
- Low profile package
- Easy pick and place
- Ultrafast recovery times for high efficiency
- For use as freewheeling and snubber diodes
- Built-in strain relief, ideal for automated placement
- High temperature soldering guaranteed:
250°C/10 seconds on terminals

Maximum Ratings & Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	BYGR20D	BYGR20G	BYGR20J	Unit
Device Marking Code		BD	BG	BJ	
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	V
Maximum RMS voltage	V _{RMS}	140	280	420	V
Maximum DC blocking voltage	V _{DC}	200	400	600	V
Maximum average forward rectified current (see fig.1)	I _{F(AV)}		1.6		A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}		30		A
Maximum thermal resistance	R _{θJA} R _{θJL}	Junction to Ambient ⁽¹⁾			°C/W
Junction to Lead		80 20			
Operating and storage temperature range	T _J , T _{STG}	−55 to +150			°C

Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Maximum instantaneous forward voltage at 1.0A at 1.5A	V _F	1.3 1.4	V
Maximum DC reverse current T _A = 25°C at rated DC blocking voltage T _A = 100°C	I _R	1 10	μA
Maximum reverse recovery time at I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}	75	ns

Surface Mount Ultrafast Rectifiers

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 - Max. Average Forward Current vs. Ambient Temperature

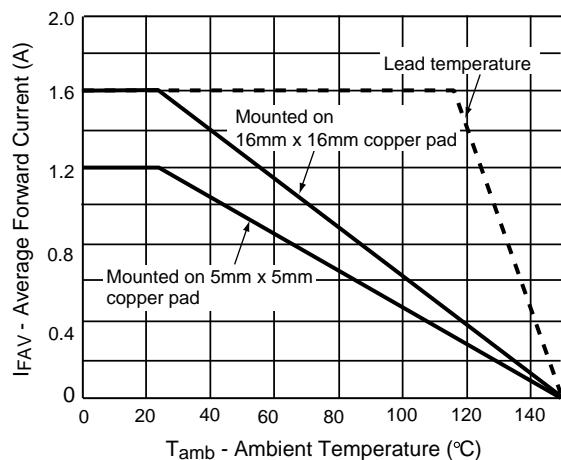


Fig. 2 – Typical Instantaneous Forward Characteristics

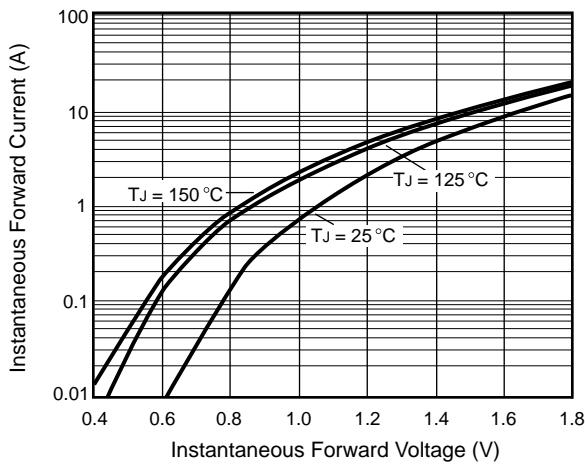


Fig. 3 – Typical Reverse Leakage Characteristics

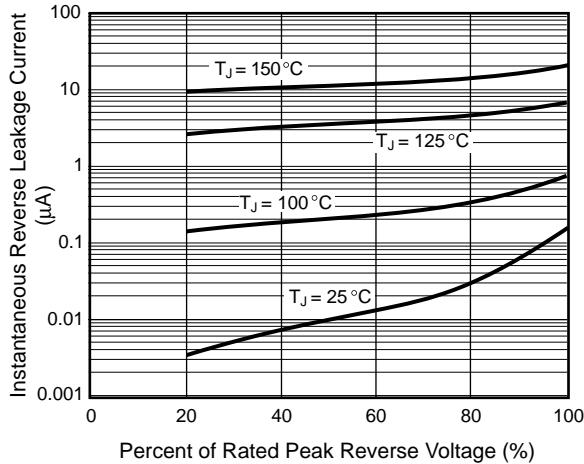


Fig. 4 – Typical Junction Capacitance

